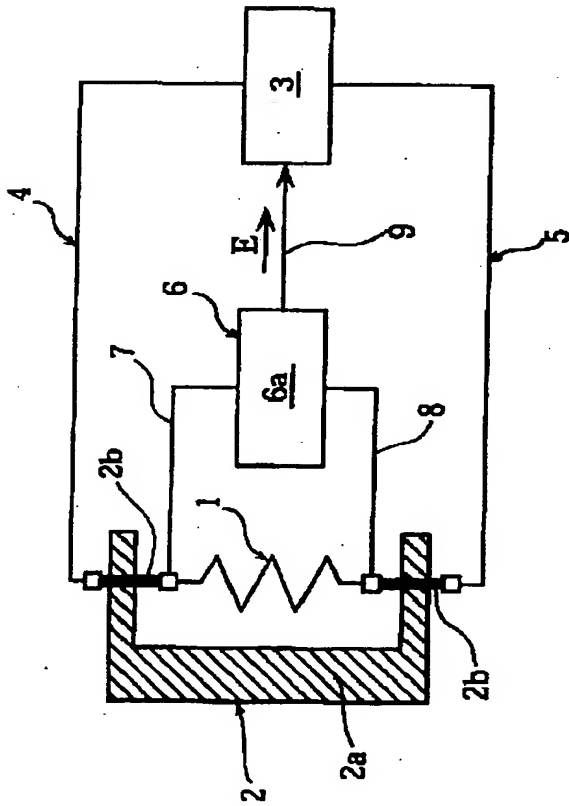
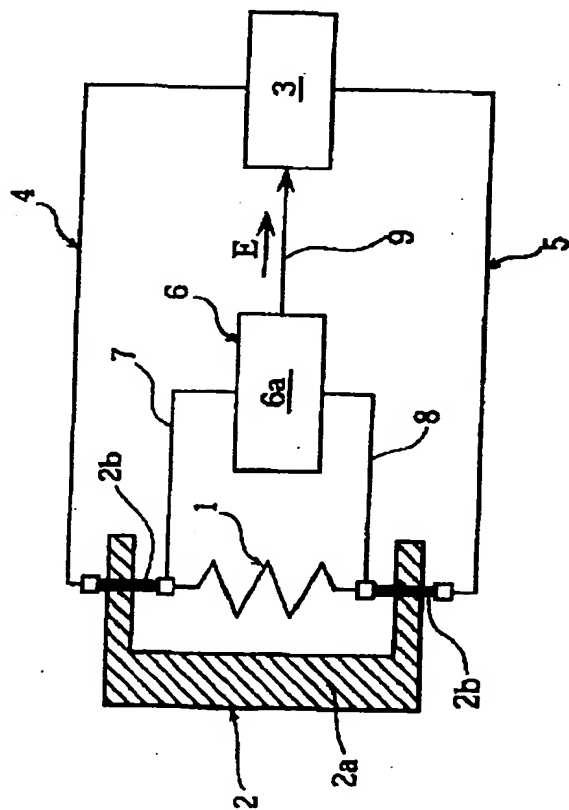


<p><b>2001-573698/65</b> M29  <b>MITSUBISHI CABLE IND LTD</b>          1999.09.28 1999-275013(+1999JP-275013) (2001.04.13) G01N 3/60,          27/04, G12B 1/00 // C22F 1/00  <b>Heat cycle testing device for shape memory alloy involves measuring resistance change during heating, and supplying resistance-change-derived feedback signal to current-heat supply controller</b>  <b>C2001-170682</b></p>	<p>M(29-E)</p> <p>performed within a short time. Also characteristics evaluation in the middle of confirmatory tests can be performed.</p> <p><b>DESCRIPTION OF DRAWING</b>          The figure shows the structure explanatory drawing of heat cycle testing device.          Shape memory alloy 1          Holder 2          Current-heat supply controller 3          Measurement unit 6          Feedback signal E</p>
<p><b>NOVELTY</b>          Current-heat supply controller (3) supplies current and heat to shape memory alloy (1) held in a holder (2). The resistance of memory alloy (1) is changed corresponding to the heat supplied by the controller (3), and resistance is measured by measurement unit (6). A feedback signal (E) is sent from the resistance value measurement unit based on measured resistance to electric heat controller.</p> <p><b>USE</b>          Heat cycle testing device for shape memory alloy.</p> <p><b>ADVANTAGE</b>          Reduces measuring time of each cycle. Several tests can be</p>	<p>JP 2001099770-A+</p>

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